Innovative Service Around the Globe

DATA SHEET

SURFACE-MOUNT CERAMIC MULTILAYER CAPACITORS

01005

NPO/X5R/X7R

4 V TO 16 V

10 pF to 100 nF

RoHS compliant & Halogen Free



YAGEO Phícomp



SCOPE

This specification describes 01005 NP0/X5R series chip capacitors with lead-free terminations.

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APPLICATIONS

- Mobile
- Module

FEATURES

- Supplied in tape on reel
- Nickel-barrier end termination
- RoHS compliant
- Halogen Free compliant

ORDERING INFORMATION-GLOBAL PART NUMBER, PHYCOMP CTC & 12NC

All part numbers are identified by the series, size, tolerance, TC material, packing style, voltage, process code, termination and capacitance value.

YAGEO BRAND ordering code

GLOBAL PART NUMBER (PREFERRED)

<u>xxxx x x xxx x</u> B <u>x xxx</u> (1) (2) (3) (4) (5) (6) (7)

(I) SIZE - INCH BASED (METRIC)

0100(0402)

(2) TOLERANCE

 $| = \pm 5\%$

 $K = \pm 10\%$

 $M = \pm 20\%$

(3) PACKING STYLE

R = Paper/PE taping reel; Reel 7 inch

(4) TC MATERIAL

NP0

X5R

X7R

(5) RATED VOLTAGE

2 = 4 V

5 = 6.3 V

6 = 10 V

7 = 16 V

(6) PROCESS

N = NP0

B = Class 2 MLCC

(7) CAPACITANCE VALUE

2 significant digits+number of zeros

The 3rd digit signifies the multiplying factor, and letter R is decimal point

Example: $121 = 12 \times 10^{1} = 120 \text{ pF}$

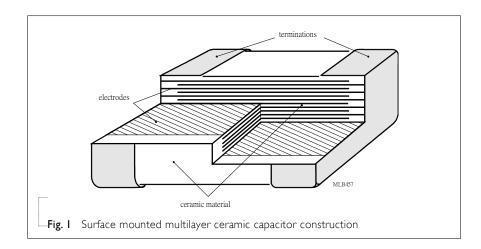


CONSTRUCTION

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The capacitor consists of a rectangular block of ceramic dielectric in which a number of interleaved metal electrodes are contained. This structure gives rise to a high capacitance per unit volume.

The inner electrodes are connected to the two end terminations and finally covered with a layer of plated tin (NiSn). The terminations are lead-free. A cross section of the structure is shown in Fig.1.

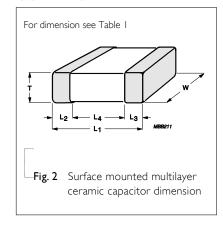


<u>DIMENSION</u>

Table I For outlines see fig. 2

TYPE	L _I (mm)	W (mm)	T (mm)	L_2 / L_3 min.	(mm) max.	L ₄ (mm) min.
01005	0.4 ±0.02	0.2 ±0.02	0.2 ±0.02	0.07	0.14	0.13

OUTLINES





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CAPACITANCE RANGE & THICKNESS

Surface-Mount Ceramic Multilayer Capacitors

Table 2 01		<u> </u>	<u> </u>					
CAP.	NP0	CAP.	X5R			CAP.	X7R	
	10V / 16 V		4V	6.3V	10V		6.3V / IOV	16V
0.5 pF	0.2±0.02	100 pF	0.2±0.02	0.2±0.02	0.2±0.02	100 pF	0.2±0.02	0.2±0.02
0.6 pF	0.2±0.02	150 pF	0.2±0.02	0.2±0.02	0.2±0.02	150 pF	0.2±0.02	0.2±0.02
0.7 pF	0.2±0.02	220 pF	0.2±0.02	0.2±0.02	0.2±0.02	220 pF	0.2±0.02	0.2±0.02
0.8 pF	0.2±0.02	330 pF	0.2±0.02	0.2±0.02	0.2±0.02	330 pF	0.2±0.02	0.2±0.02
0.9 pF	0.2±0.02	470 pF	0.2±0.02	0.2±0.02	0.2±0.02	470 pF	0.2±0.02	0.2±0.02
1.0 pF	0.2±0.02	680 pF	0.2±0.02	0.2±0.02	0.2±0.02	680 pF	0.2±0.02	0.2±0.02
1.2 pF	0.2±0.02	1 000 pF	0.2±0.02	0.2±0.02	0.2±0.02	1 000 pF	0.2±0.02	0.2±0.02
1.5 pF	0.2±0.02	2.2 nF	0.2±0.02	0.2±0.02	0.2±0.02	2.2 nF		
1.8 pF	0.2±0.02	4.7 nF	0.2±0.02	0.2±0.02	0.2±0.02	4.7 nF		
2.2 pF	0.2±0.02	10 nF	0.2±0.02	0.2±0.02	0.2±0.02	10 nF		
2.7 pF	0.2±0.02	22nF	0.2±0.02	0.2±0.02		22nF		
3.3 pF	0.2±0.02	47 nF	0.2±0.02	0.2±0.02		47 nF		
3.9 pF	0.2±0.02	100 nF	0.2±0.02	0.2±0.02		100 nF		
4.7 pF	0.2±0.02	220 nF	0.2±0.02			220 nF		
5.6 pF	0.2±0.02	Tape width	-	8 mm		Tape width	8 mr	n
6.8 pF	0.2±0.02							
8.2 pF	0.2±0.02							
10 pF	0.2±0.02							
12 pF	0.2±0.02							
15 pF	0.2±0.02							



18 pF

22 pF

27 pF

33 pF 39 pF

47 pF

56 pF

68 pF

82 pF

100 pF

Tape width

0.2±0.02

0.2±0.02

0.2±0.02 0.2±0.02

0.2±0.02

0.2±0.02

0.2±0.02

0.2±0.02

0.2±0.02

 0.2 ± 0.02

8 mm

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NP0/X5RX7R

6.3V to 16V

THICKNESS CLASSES AND PACKING QUANTITY

 Ta	Ы	le	3

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SIZE	THICKNESS	TAPE WIDTH -	Ø180 MN	1 / 7 INCH	Ø330 MN	1 / 13 INCH	OUANTITY
CODE		QUANTITY PER REEL	Paper/PE	Blister	Paper/	Blister	PER BULK CASE
01005	0.2 ±0.02 mm	8 mm	20,000				

ELECTRICAL CHARACTERISTICS

NP0/X5R DIELECTRIC CAPACITORS; NISN TERMINATIONS

Unless otherwise specified, all test and measurements shall be made under standard atmospheric conditions for testing as given in 5.3 of IEC 60068-1:

Temperature: 15 °C to 35 °C
Relative humidity: 25% to 75%
Air pressure: 86 kPa to 106 kPa

Before the measurements are made, the capacitor shall be stored at the measuring temperature for a time sufficient to allow the entire capacitor to reach this temperature.

The period as prescribed for recovery at the end of a test is normally sufficient for this purpose.

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VALUE
10 pE+0 100 pE
10 pr to 100 m
±5%, ±10%
±10%, ±20%
≤ I / (400 + 20C)
≤ 0.1 %
≤ 10 %
$R_{ins} \ge 10 \text{ G}\Omega$ or $R_{ins} \times C \ge 500$ seconds whichever is less
X5R/X7R≥ InF:
Rins × C ≥ $100 \Omega \cdot F$
X5R ≥ 10nF:
Rins \times C \geq 50 $\Omega \cdot$ F
±30 ppm/°C
±15%
-55 °C to +125 °C
-55 °C to +85 °C



X7R

-55 °C to +125 °C

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SOLDERING RECOMMENDATION
——Table 5

SOLDERING SIZE METHOD 01005

Reflow Reflow only

Reflow/Wave

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TESTS AND REQUIREMENTS

Table 6 Test procedures and requirements

TEST	TEST MET	HOD	PROCEDURE	REQUIREMENTS
Mounting	IEC 60384- 21/22	4.3	The capacitors may be mounted on printed-circuit boards or ceramic substrates	No visible damage
Visual Inspection and Dimension Check		4.4	Any applicable method using × 10 magnification	In accordance with specification
Capacitance		4.5.1	Class I: $f = I \text{ MHz for } C \leq I \text{ nF, measuring at voltage } I \text{ V}_{rms} \text{ at } 20 \text{ °C}$ $f = I \text{ KHz for } C > I \text{ nF, measuring at voltage } I \text{ V}_{rms} \text{ at } 20 \text{ °C}$ Class 2: $f = I \text{ KHz, measuring at voltage } 0.5 \text{ Vrms at } 20 \text{ °C}$	Within specified tolerance
Dissipation Factor (D.F.)		4.5.2	Class I: $f = 1 \text{ MHz for C} \le 1 \text{ nF , measuring at voltage 1 V}_{rms} \text{ at } 20 \text{ °C}$ $f = 1 \text{ KHz for C} > 1 \text{ nF, measuring at voltage 1 V}_{rms} \text{ at } 20 \text{ °C}$ Class 2: $f = 1 \text{ KHz, measuring at voltage } 0.5 \text{ Vrms at } 20 \text{ °C}$	In accordance with specification
Insulation Resistance		4.5.3	At Ur (DC) for I minute	In accordance with specification



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TEST TEST METHOD PROCEDURE

Temperature coefficient

4.6 Capacitance shall be measured by the steps shown in the following table.

> The capacitance change should be measured after 5 min at each specified temperature stage.

	-
Step	Temperature(°C)
a	25±2
Ь	Lower temperature±3°C
С	25±2
d	Upper Temperature±2℃
е	25±2

(I) Class I

Temperature Coefficient shall be calculated from the formula as below

Temp, Coefficient =
$$\frac{C2 - C1}{C1 \times \Delta T} \times 10^6 \text{ [ppm/°C]}$$

C1: Capacitance at step c

C2: Capacitance at 125℃

 ΔT : 100°C(=125°C-25°C)

Measuring Voltage: 0.5 to 5 Vrms

(2) Class II

Capacitance Change shall be calculated from the formula as below

$$\Delta C = \frac{C2 - C1}{C1} \times 100\%$$

C1: Capacitance at step c

C2: Capacitance at step b or d

REQUIREMENTS

<General purpose series>

Class I:

 Δ C/C: ± 30 ppm

Class2:

X7R: Δ C/C: \pm 15% Y5V: ∆ C/C: 22~-82%

<High Capacitance series>

Class2:

 \times 7R/ \times 5R: Δ C/C: \pm 15%

Y5V: Δ C/C: 22~-82%

In case of applying voltage, the capacitance change should be measured after I more min. with applying voltage in equilibration of each temp. stage.

CC0100MRX5R5BB104:

0.2V±0.1Vrms

Adhesion

IEC 60384-21/22

4.7

A force applied for 10 seconds to the line joining the terminations and in a plane parallel to the

substrate

Force

size 01005: 1N

Bond Strength of Plating on **End Face**

4.8 Mounting in accordance with IEC 60384-22

paragraph 4.3

Conditions: bending I mm at a rate of I mm/s, radius jig 5 mm

No visible damage

 Δ C/C

Class I:

NP0: within $\pm 1\%$ or 0.5 pF, whichever is greater

Class2:

X5R: ±10%



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TEST	TEST METH	HOD	PROCEDURE	REQUIREMENTS
Resistance to Soldering Heat		4.9	Precondition: 150 +0/-10 °C for I hour, then keep for 24 ±1 hours at room	Dissolution of the end face plating shall not exceed 25% of the length of the edge concerned
			temperature Preheating: I20 °C to I50 °C for I minute and I70 °C to 200 °C for I minute. Solder bath temperature: 260 ±5 °C Dipping time: I0 ±0.5 seconds	$\Delta C/C$ Class 1: NP0: within $\pm 0.5\%$ or 0.5 pF, whichever is greater Class2: X5R: $\pm 10\%$
			Recovery time: 24 ±2 hours	D.F. within initial specified value R _{ins} within initial specified value
Solderability		4.10	Preheated the temperature of 80 °C to 140 °C and maintained for 30 seconds to 60 seconds.	The solder should cover over 95% of the critical area of each termination
			Test conditions for leadfree containing solder alloy	
			Temperature: 245 \pm 5 °C Dipping time: 3 \pm 0.3 seconds Depth of immersion: 10 mm	
Rapid Change of	IEC 60384- 21/22	4.11	Preconditioning; I50 +0/–I0 °C for I hour, then keep for	No visual damage
Temperature			24 ±1 hours at room temperature	ΔC/C
			5 cycles with following detail: 30 minutes at lower category temperature 30 minutes at upper category temperature Recovery time 24 ±2 hours	Class 1: NP0: within ±1% or 1 pF, whichever is greater Class2: X5R: ±15%
			,	D.F. meet initial specified value R _{ins} meet initial specified value



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TEST	TEST METHOD	PROCEDURE	REQUIREMENTS
Damp Heat	with Ur 4.13		REQUIREMENTS No visual damage after recovery ΔC/C Class 1: NP0: within ±2% or 1 pF, whichever is greater Class2: X5R: ±20%
		500 ±12 hours at 40 ±2 °C; 90 to 95% R.H; I.0 Ur applied. 4. Recovery: Class I: 6 to 24 hours Class 2: 24 ±2 hours 5. Final measure: C, D, IR P.S. If the capacitance value is less than the minimum value permitted, then after the other measurements have been made the capacitor shall be precondition according to "IEC 60384 4.1" and then the requirement shall be met.	D.F. Class 1: NP0: \leq 2 × specified value Class2: X5R: \leq 2 × specified value R_{ins}
			Class I: $ \begin{tabular}{l} NP0: $\geq 2,500 \ M\Omega \ or \ R_{ins} \times C_r \geq 25s \ whichever is less \\ Class2: $\times 5R: $\geq 500 \ M\Omega \ or \ R_{ins} \times C_r \geq 25s \ whichever is less \\ \times 5R \geq \ln F \\ Δ C/C \\ Class2: $\times 5R: $\pm 25\%$ D.F. \\ Class2: $\times 5R: $\leq 2 \times specified \ value \\ Rins \\ Rins \times Cr \geq 5 \ \Omega \cdot F \\ \end{tabular} $



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TEST	TEST METHO	DD	PROCEDURE	REQUIREMENTS
TEST Endurance		DD 4.14	 Preconditioning, class 2 only: 150 +0/-10 °C /I hour, then keep for 24 ± I hour at room temp Initial measure: Spec: refer initial spec C, D, IR Endurance test: Temperature: NP0: 125 °C Specified stress voltage applied for I,000 hours:	REQUIREMENTS No visual damage $\Delta C/C$ Class I: NP0: within $\pm 2\%$ or I pF, whichever is greater Class2: X5R: $\pm 20\%$ D.F. Class I: NP0: $\leq 2 \times \text{specified value}$ Class2: X5R: $\leq 2\times \text{ initial value max}$ R_{ins} Class I: NP0: $\geq 4,000 \text{ M}\Omega$ or $R_{\text{ins}} \times C_r \geq 40 \text{s whichever is less}$
		be precondition according	measurements have been made the capacitor shall be precondition according to "IEC 60384 4.1" and then the requirement shall be met.	Class2: $X5R: \ge 1,000 \text{ M}\Omega \text{ or}$ Rins \times Cr $\ge 50s$ whichever is less $X5R \ge 1nF$ Δ C/C Class2: $X5R: \pm 25\%$ D.F. Class2: $X5R: \le 2x$ initial value max Rins Class2: Rins \times Cr $\ge 10 \Omega \cdot F$
Voltage Proof	IEC 60384-1	4.5.4	Specified stress voltage applied for 1 minute $U_r \le 100 \text{ V}$: series applied 2.5 U_r l: 7.5 mA	No breakdown or flashover



NP0/X5RX7R

6.3V to 16V

REVISION HISTORY

REVISION	DATE	CHANGE NOTIFICATION	DESCRIPTION
Version 7	Oct. 31, 2015		- Capacitance range & thickness update
Version 6	Jun. 29, 2015		-Test procedures and requirements
Version 5	Jun. 06, 2013		-Test procedures and requirements
Version 4	Mar. 27, 2013		- Change Tolerance
Version 3	Jan. 15, 2013		- Change Range
Version 2	Oct. 23, 2012		- Change Range
Version I	July 03, 2012		- Change Range
Version 0	Apr 16, 2012	-	- New

